

IN THE SPECIFICATION

Please amend the specification as indicated below.

Please insert the following header and paragraph at page 1, before the Background of the Invention section.

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. Patent Application Serial No. 10/306,627,
PAT 6,717,248
filed November 26, 2002/which was a continuation of U.S. Patent Application Serial No. 09/566,069, filed May 5, 2000, now U.S. Patent No. 6,515,356, issued on February 4, 2003.

Please amend the paragraph beginning on page 6, line 26 as follows:

The present invention also provides a method for fabricating a semiconductor ~~package~~ package. One embodiment within the present invention includes the steps of: providing a circuit board having a plurality of bond fingers and ball lands, the circuit board having a through hole formed at the center thereof; locating a semiconductor chip having a plurality of input/output pads at one face thereof in the through hole of the circuit board; electrically connecting the input/output pads of the semiconductor chip to the bond fingers of the circuit board through an electrical conductor such as bond wires; encapsulating the semiconductor chip, conductors, and a predetermined region of the circuit board with an encapsulant; and fusing conductive balls to the ball lands of the circuit board, to form input/output terminals.

Please amend the paragraph beginning on page 17, line 21 as follows:

Referring to FIG. 6, a predetermined circuit pattern layer can be formed on second face 11b of resin film 11 (BT epoxy resin film), as well as on first face 11a thereof. Specifically, first face 11a of resin film 11 has the circuit pattern layer composed of bond fingers 12, connection parts 13 and ball lands 15 formed thereon, and second face 11b also has a circuit pattern layer including connection parts 13 formed thereon. Here, the circuit pattern layers formed on first face 11a and second face 11b of resin film can be connected to